Call for Papers

Main areas covered by the conference: Materials, devices and systems science, engineering and architectures and their characterization available soon

Papers are requested in the following areas:

- **Integrated Circuit and System Design**
  Mixed-signal, analogue and digital circuits and systems for high speed and/or low power consumption, adaptive power management, RF up to sub-THz, low costs, and advanced performance and density, circuits in More than Moore and Beyond Moore technologies. Manufacturing challenges (cost and cycle time reduction, test, wafer - prime - production etc..)

- **More Moore and Beyond Moore Devices Technologies and Architectures**
  Ultimate CMOS (silicon and IV-IV strained alloys on insulator, multi-gate and channels transistors, III-V channels), nanowires; Thin films dielectrics: Hik and Low K; nano-materials; Beyond Moore: TunFETs, carbon electronics,…

- **Memory technologies**
  Sand alone and Embedded MemoryTechnologies, New memory technologies: RRAMs, CBRAMs, MRAMs, 1T DRAM,…

- **More than Moore technologies**
  MEMS, NEMS, power devices (GaN, GaP), RF and analog passive components (MIM, filters, supercapacitors, inductances,…); Spintronics based devices; Bio sensors, BioMEMS, BioNEMS, POC devices, Implanted devices, gas sensors, chemical sensors, Imagers, energy harvesting, thermoelectricity,…

- **Interconnection and Packaging Technologies**
  3-D and novel interconnects, Wire bonding, flip chip, solder replacement flip chip, under bump metallurgy, high density substrates, New packaging technologies for single chip, multi-chip, wafer level, power and stacked-die packages, Wafer bumping and thinning,…

- **Optical Devices and Photonics**
  Optical component assemblies, electro-optical modules, waveguides, silicon based photonic devices, organic devices, optical materials

- **Organic and flexible electronics**
  polymer and organic, ink-jet printed electronics, organic PV and PV in organic, OLEDs,…

- **Characterization, Quality and Reliability**
  Electrical characterization, testing strategies and protocols, physical characterization for process development and process control. Component, board and system level reliability assessment, failure analysis, interfacial adhesion, accelerated testing and models, component and system qualification.

- **Modeling and Simulation**
  EDA, TCAD, electrical, thermal, thermo-mechanical, reliability, optical, modeling and simulation for devices, component and system level applications.
Key Dates:

Paper submission deadline                  April 30, 2012
Paper acceptance                             June 1, 2012
Deadline for early bird registration
(accommodation, conference and short course fees) August 15, 2012

Submit Paper

Submission of papers in the areas mentioned above are encouraged and solicited to describe original work.
The paper must include the purpose, applications, results, comparison with the state-of-the-art, conclusions, visualizing pictures and key references.
All conference papers will be included in IEEE Xplore.
Papers will be presented at the conference as talks or posters.

» Please send your proposal to paper-scd@gerotron.com

Guidelines for submitted papers:

• Papers have to be formatted in accordance with the IEEE – Manuscript Templates for Conference Proceedings
• Contributions can only be accepted in English language
• Paper length: 3-4 pages, paginated with Arabic numerals at bottom right
• File format: pdf, file size max. 5 MB

In addition we need the ISCDG Paper Submission Form

http://gerotron.com/ISCDG_CfP.doc

Please fill out the form below and send this document together with your paper submission to us.

2012 International Semiconductor Conference
Dresden - Grenoble (ISCDG)
alternating venue in Dresden (Germany) and Grenoble (France) every other year
Technology, Design, Packaging, Simulation and Test
International Conference, Short Course and Table Top Exhibition
September 24 to 26, 2012 - MINATEC Campus, Grenoble, France

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CALL FOR PAPERS
Conference technical and poster sessions on Monday, September 24 and Tuesday, September 25, 2012:

Plenary Talks

Confirmed Speakers:

- André-Jacques Auberton-Hervé and Carlos Mazuré, SOITEC, Bernin, France
  “The role of SOITEC in a Future Diversified Low Power Electronics and Energy Production Demanding Market”

- Gerhard Fettweis, Technical University Dresden, Dresden, Germany
  “Future Perspectives for Mobile circuits and applications”

- U-In Chung, Samsung Advanced Institute of Technology, Yongin-City, Gyeonggi-Do, Korea
  “Prospects and Challenges for Future Nanoelectronics”

Special session

Paper submissions in the area of Energy Efficient Devices, circuits and systems are welcome.

One day Short Course on Wednesday, September 26, 2012:

“Innovative Paths for Future Applications in Information Heterogeneous Technologies”

Confirmed Speakers:

- Yoshio Nishi, Stanford University, Stanford, CA, USA
  “Scaling and Beyond. Which perspectives?”

- Bernard Dieny, Spintec, Grenoble, France
  “Spintronics”

- Laurent Vivien, Institut d’Electronique Fondamentale, Université Paris-Sud, Orsay, France
  “Photonics and Interconnect”

- Donald Martin, UJF, Grenoble, France
  “Nanobiotechnology for Energy”

Booths available to Exhibitors

Industrial forum

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